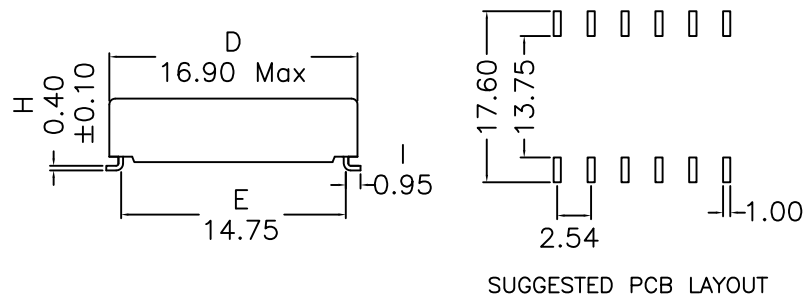
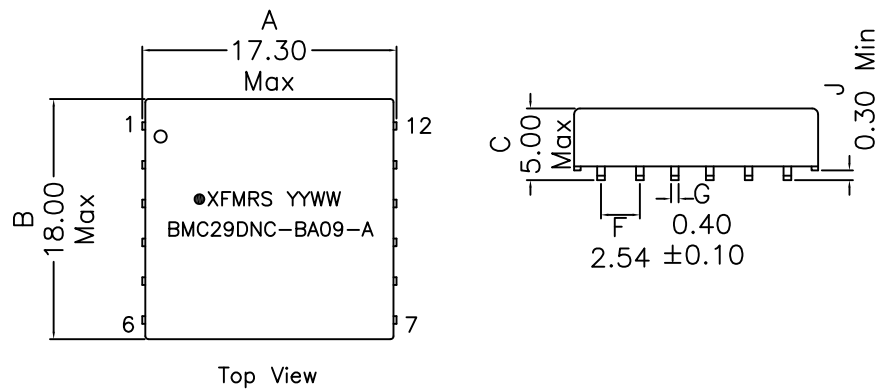
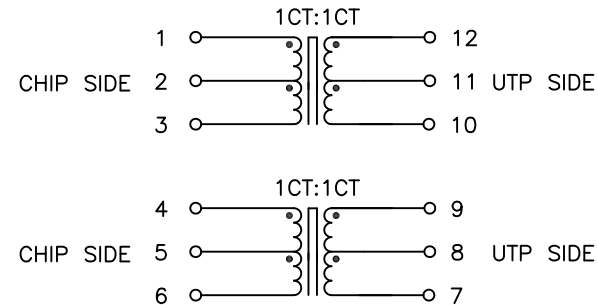


1. Mechanical Dimensions:



2. Schematic:



3. Electrical Specifications: @25°C

UTP Impedance: 100 OHMS
 Turns Ratio: (CHIP : UTP)=1CT:1CT±2%
 Isolation Voltage: 2900Vac, CHIP SIDE to UTP SIDE
 UTP Side OCL: 350uH Min @100KHz 0.1V, 8mAdc
 UTP Side Q: tbd Min @100KHz 0.1V,
 Rise Time (10–90%): 4.0ns Typical
 Insertion Loss (1–100MHz): –1.0dB Maximum
 Return Loss: 30MHz 60MHz 80MHz
 –20dB –14dB –11.5dB Typ
 CMRR: 30MHz 50MHz 100MHz
 –42dB –37dB –33dB Typ

Notes:

- Solderability: Leads shall meet MIL–STD–202G, Method 208H for solderability.
- Flammability: UL94V–0
- ASTM oxygen index: > 28%
- Insulation System: Class F 155°C. UL file E151556
- All listed parameters are to be within tolerance from –40°C to +85°C unless otherwise noted
- Storage Temperature Range: –55°C to +125°C
- Aqueous wash compatible
- SMD Lead Coplanarity: ±0.004”(0.102mm)
- Electrical and mechanical specifications 100% tested
- RoHS Compliant Component
- Recommended IR Reflow peak temp of 245C Max.

DOC. REV: A/1

PRELIMINARY

XFMRS Inc www.XFMRS.com	Title: TRANSFORMER		
	P/N:XFBMC29DNC–BA09–A REV. A		
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xx ±0.25 Dimensions in MM	DWN.	Xiang	Sep–17–15
	CHK.	YK Liao	Sep–17–15
SHEET 1 OF 1	APP.	BSJ	Sep–17–15

PROPRIETARY

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